

International Application No.: PCT/JP2004/015621

U.S. Patent Application No.: Unknown

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Page 2 of 10

**AMENDMENTS TO THE SPECIFICATION:**

A substitute specification and a marked-up copy of the English translation of the originally filed PCT application are attached hereto.

Please replace the Title of the Invention originally filed with the above-identified patent application with the following new Title:

METHOD FOR FORMING THICK FILM PATTERN, METHOD FOR  
MANUFACTURING ELECTRONIC COMPONENT, AND PHOTOLITHOGRAPHY  
PHOTOSENSITIVE PASTE